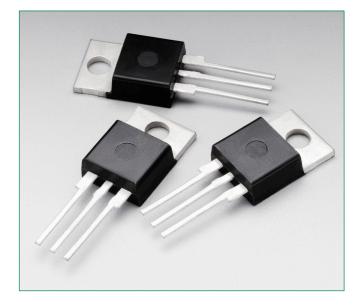
Surface Mount - 50 - 800V > 2N6394

# 2N6394

**Pin Out** 

ittelfuse

Expertise Applied | Answers Delivered



# Description

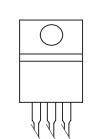
Designed primarily for half-wave ac control applications, such as motor controls, heating controls and power supplies.

Po

#### Features

- Glass Passivated Junctions for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Construction for Low Thermal Resistance, High Heat Dissipation and Durability
- Gate Triggering Guaranteed in all Four Quadrants
- For 400 Hz Operation, Consult Factory
- 8.0 A Devices Available as 2N6344 thru 2N6349
- Pb-Free Package is Available





# Functional Diagram

# Additional Information



Datasheet



U

Samples



### Surface Mount -50 - 800V > 2N6394

#### Maximum Ratings $\dagger$ (T<sub>J</sub> = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off-State Voltage (Note 1) (T <sub>J</sub> = -40 to 110°C, Sine Wave, 50 to 60 Hz, Gate Open) 2N639 2N639 2N639 2N639	5 V <sub>RRM</sub> 7	50 100 400 800	V
On-State RMS Current (180° Conduction Angles; T <sub>c</sub> = 90°C)	I <sub>T (RMS)</sub>	12	A
Peak Non–Repetitive Surge Current (1/2 Cycle, Sine Wave, 60 Hz, T <sub>J</sub> = 90°C)	I <sub>TSM</sub>	100	A
Circuit Fusing Considerations (t = 8.3 ms)	I <sub>2t</sub>	40	A²s
Forward Peak Gate Power (Pulse Width $\leq$ 1.0 $\mu s, T_c$ = 90°C)	P <sub>GM</sub>	20	W
Forward Average Gate Power (t = 8.3 ms, $T_c = 90^{\circ}C$ )	P <sub>G(AV)</sub>	0.5	W
Forward Peak Gate Current (Pulse Width $\leq$ 1.0 $\mu s, T_c$ = 90°C)	I <sub>GM</sub>	2.0	А
Operating Junction Temperature Range	TJ	-40 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to +125	°C

†Indicates JEDEC Registered Data

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

#### **Maximum Ratings †** ( $T_{J} = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit
Thermal Resistance, Junction to Case	R <sub>sJC</sub>	2.0	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	TL	260	°C

† Indicates JEDEC Registered Data..

## Surface Mount - 50 - 800V > 2N6394

#### Electrical Characteristics - OFF (T<sub>c</sub> = 25°C unless otherwise noted; Electricals apply in both directions)

Characteristic		Symbol	Min	Тур	Max	Unit
tPeak Repetitive Blocking Current	$T_{J} = 25^{\circ}C$	I <sub>DRM</sub> ,	-	-	1.0	μA
$(V_{AK} = V_{DRM} = V_{RRM}; Gate Open)$	$T_{J} = 125^{\circ}C$	I <sub>RRM</sub>	-	-	2.0	mA

# **Electrical Characteristics** $\cdot$ **ON** (T<sub>c</sub> = 25°C unless otherwise noted; Electricals apply in both directions)

Characteristic	Symbol	Min	Тур	Max	Unit
†Peak Forward On–State Voltage (Note 2) ( $I_{TM} = 24$ A Peak)	V <sub>TM</sub>	-	1.7	2.2	V
†Gate Trigger Voltage (Continuous DC), All Quadrants (Continuous dc) ( $V_D = 12$ Vdc, $R_L = 100$ Ohms)	I <sub>GT</sub>	_	5.0	30	mA
†Gate Trigger Voltage (Continuous dc) (V $_{\rm D}$ = 12 Vdc, R $_{\rm L}$ = 100 Ohms)	V <sub>GT</sub>	-	0.7	1.5	V
Gate Non–Trigger Voltage ( $V_D = 12$ Vdc, $R_L = 100$ Ohms, $T_J = 125^{\circ}$ C)	V <sub>gd</sub>	0.2	_	_	V
†Holding Current ( $V_{D} = 12$ Vdc, Initiating Current = 200 mA, Gate Open)	I <sub>H</sub>	_	6.0	50	mA
Turn-On Time ( $I_{TM}$ = 12 A, $I_{GT}$ = 40 mAdc, $V_{D}$ = Rated $V_{DRM}$ )	t <sub>gt</sub>	-	1.0	2.0	μs
Turn-Off Time ( $V_{D}$ = Rated $V_{DRM}$ ) ( $I_{TM}$ = 12 A, $I_{R}$ = 12 A)		-	-	15	
$(I_{TM} = 12 \text{ A}, I_{R} = 12 \text{ A}, T_{J} = 125^{\circ}\text{C})$	t <sub>q</sub>	-	-	35	μs

†Indicates JEDEC Registered Data

2. Pulse Test: Pulse Width  $\leq$  300  $\mu sec, \, Duty \, Cycle \leq 2\,\%.$ 

#### **Dynamic Characteristics**

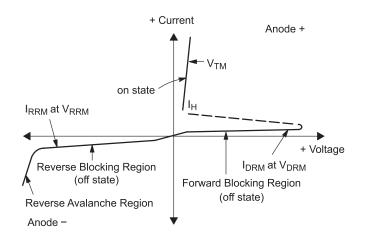
Characteristic	Symbol	Min	Тур	Max	Unit
Critical Rate–of–Rise of Off-State Voltage Exponential ( $V_D = Rated V_{DRM}, T_J = 125^{\circ}C$ )	dv/dt(c)	-	50	_	V/µs

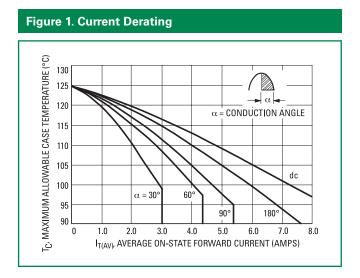


Surface Mount -50 - 800V > 2N6394

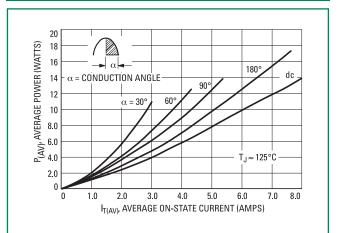
#### Voltage Current Characteristic of SCR

Symbol	Parameter	
V <sub>drm</sub>	Peak Repetitive Forward Off State Voltage	
I <sub>DRM</sub>	Peak Forward Blocking Current	
V <sub>RRM</sub>	Peak Repetitive Reverse Off State Voltage	
I <sub>RRM</sub>	Peak Reverse Blocking Current	
V <sub>TM</sub>	Maximum On State Voltage	
I <sub>H</sub>	Holding Current	





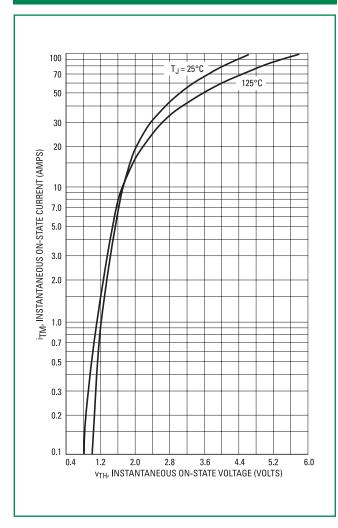
#### Figure 2. Maximum On-State Characteristics



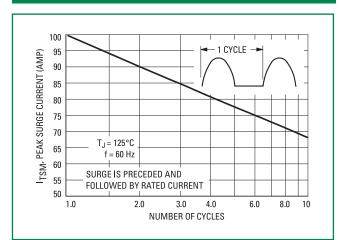


Surface Mount -50 - 800V > 2N6394

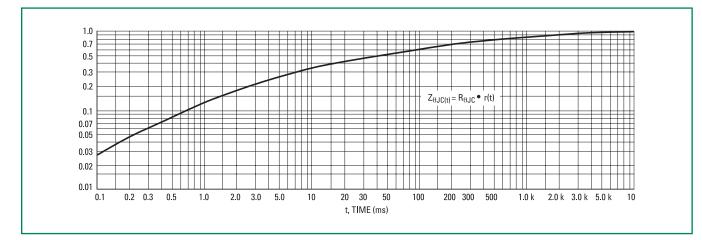
#### Figure 3. On–State Characteristics



#### Figure 4. Maximum Non-Repetitive Surge Current



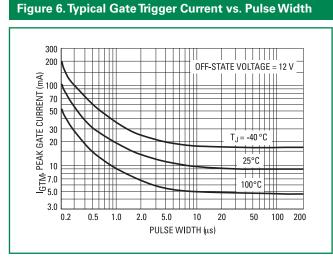
#### Figure 5. Typical Thermal Response



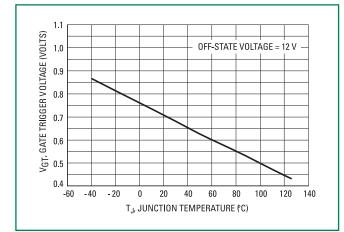


Surface Mount -50 - 800V > 2N6394

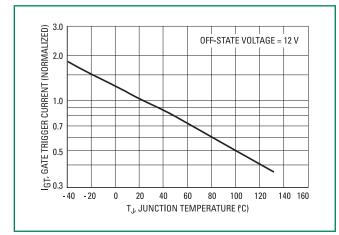
#### **Typical Characteristics**



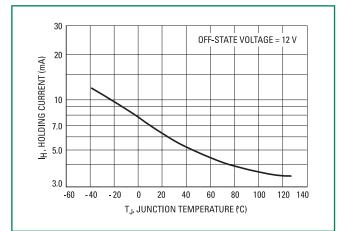
#### Figure 8. Typical Gate Trigger Voltage vs. Temperature



#### Figure 7. Typical Gate Trigger Current vs. Temperature



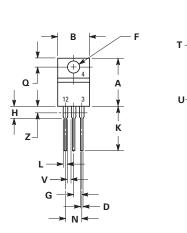
#### Figure 9. Typical Holding Current vs. Temperature

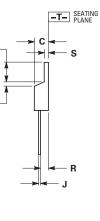




Surface Mount -50 - 800V > 2N6394

#### Dimensions





5	Inches		Millimeters		
Dim	Min	Max	Min	Max	
А	0.570	0.620	14.48	15.75	
В	0.380	0.405	9.66	10.28	
С	0.160	0.190	4.07	4.82	
D	0.025	0.035	0.64	0.88	
F	0.142	0.147	3.61	3.73	
G	0.095	0.105	2.42	2.66	
Н	0.110	0.155	2.80	3.93	
J	0.014	0.022	0.36	0.55	
K	0.500	0.562	12.70	14.27	
L	0.045	0.060	1.15	1.52	
Ν	0.190	0.210	4.83	5.33	
Q	0.100	0.120	2.54	3.04	
R	0.080	0.110	2.04	2.79	
S	0.045	0.055	1.15	1.39	
Т	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
V	0.045		1.15		
Z		0.080		2.04	

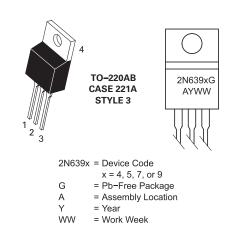
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

2. CONTROLLING DIMENSION: INCH.

3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

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#### Part Marking System



Pin Assignment				
1	Cathode			
2	Anode			
3	Gate			
4	Anode			

#### **Ordering Information**

Device	Package	Shipping
2N6394G		500 Units / Box
2N6394TG		50 Units / Box
2N6395G		500 Units / Box
2N6397G	TO-220AB (Pb-Free)	500 Units / Box
2N6397TG		50 Units / Box
2N6399G		500 Units / Box
2N6399TG		50 Units / Box

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